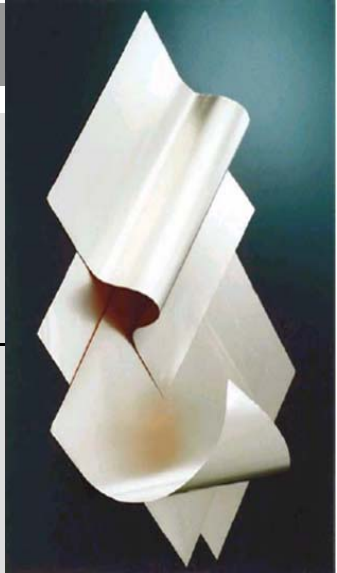


**Flexible Copper Clad Laminates** **R-F775**

Standard size warp    weft mm	Polyimide film thickness	Copper foil type	Copper foil thickness
			9 µm
700 x 510		Rolled	12 µm
1050 x 510	20 µm		18 µm
1100 x 510	25 µm		35 µm
1250 x 510	35 µm		
roll x 250	50 µm	Electro- deposited	9 µm
roll x 500			12 µm
			18 µm



Other thicknesses on request

[ **Features** ]

- ▶ Flexible copper clad laminates based on polyimide film
- ▶ Adhesiveless type due to laminate method
- ▶ High solder heat resistance achieved through low water absorption
- ▶ High copper-foil peel strength, dimensional stability and flexibility
- ▶ Single side clad version R-F770 available
- ▶ On request: R-F785 / R-F780 thin PI 14 µm and 25 µm  
                   R-F551 / R-F552 single side clad (casting method)  
                   Coverlayer (halogenfree) R - CAES

[ **Applications** ]

Hing part of cellular phone and PDA, liquid cristal driver, optical pick-up drive part, camera part in cellular phone, digital video camera, digital camera, etc